

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739420000

Status:

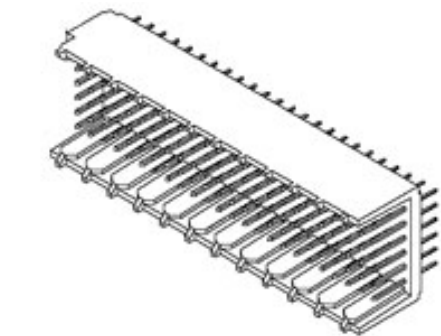
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 72 Circuits



Series

image - Reference only

Documents:

- [3D Model](#)
- [Drawing \(PDF\)](#)
- [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73942

Application

Backplane

Comments

Solder Tail

Component Type

PCB Header

Overview

[hdm](#)

Product Name

HDM®

Style

N/A

Physical

Circuits (Loaded)

72

Circuits (maximum)

72

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Number of Columns

12

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length (in)

0.079 In

PC Tail Length (mm)

2.00 mm

PCB Retention

None

PCB Thickness Recommended (in)

0.098 In

PCB Thickness Recommended (mm)

2.50 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.079 In

Pitch - Mating Interface (mm)

2.00 mm

Plating min: Mating (µin)

30

Plating min: Mating (µm)

0.75

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Stackable

Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55°C to +105°C

EU RoHS

ELV and RoHS
Compliant
REACH SVHC
Not Reviewed
Halogen-Free
Status

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73942Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Termination Interface: Style	Through Hole
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Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

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10

9

8

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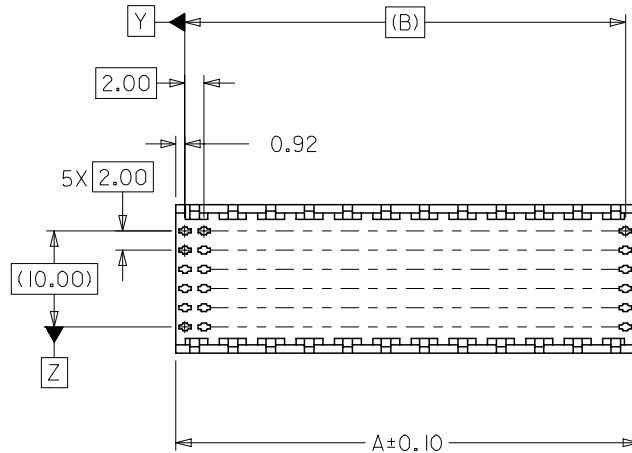
3

2

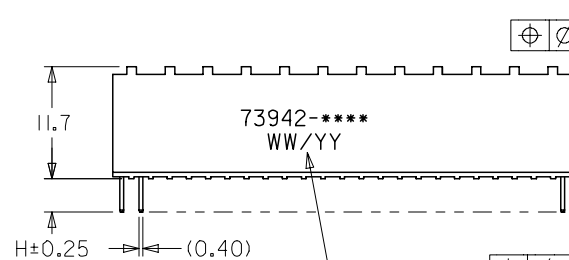
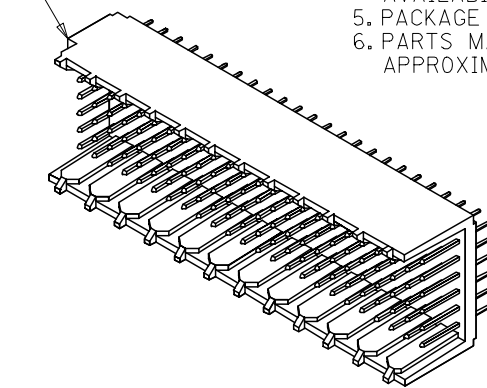
73942

NOTES:

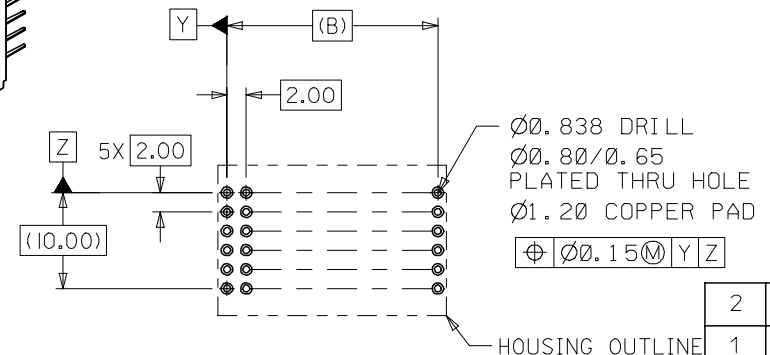
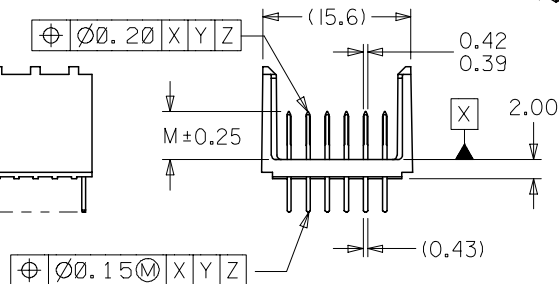
1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA;
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA;
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



LOCATING NOTCH



SEE NOTE 6



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

2	A
1	G
SHT	REV

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRAWN:MSI BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY JB INGHAM	DATE 1998/01/13	SALES ASSY HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION					
			4 PLACES	± ---	± ---	CHECKED BY	DATE						
			3 PLACES	± ---	± ---	SREED	1998/01/13						
			2 PLACES	± 0.05	± ---	APPROVED BY	DATE						
			1 PLACE	± 0.10	± ---	CBIXLER	1998/01/13	 MOLEX INCORPORATED	SD-73942-001				
			ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.					SHEET NO.	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART							1 OF 2	
			REV	G				SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

MATERIAL NUMBER ASSIGNMENT

73942-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	23.84	22.00	2.0
1	144	47.84	46.00	2.0
2	72	23.84	22.00	2.5
3	144	47.84	46.00	2.5
4	72	23.84	22.00	3.0
5	144	47.84	46.00	3.0
6	72	23.84	22.00	3.5
7	144	47.84	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC No. U81577 DRWN:JBINGHAM 98/0203 CHK: SREED 98/0203 APPR:CBIXLER 98/0203 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE --:--	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION		DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV
			mm	INCH	DRAWN BY & DATE JBINGHAM 98/01/13		TITLE: SALES ASSY, HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION					
		4 PLACES	±0.	±.	CHECKED BY & DATE SREED 98/01/13		MOLEX INCORPORATED					
		3 PLACES	±0.	±.	APPROVED BY & DATE CBIXLER 98/01/13							
		2 PLACES	±0.N/A	±.	CAD FILENAME S73942X2.DGN		MATERIAL NO. SEE CHART	DRAWING NO. SD-73942-001	SHEET NO. 2			
		1 PLACE	±0.N±A	±.	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					SIZE B

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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